

## SPECIAL INTEREST GROUPS (SIG's)

A Special Interest Group (SIG) is a cross functional collection of people who meet to pursue and share knowledge and information on a specific topic of interest usually relating to a problematic Rel. concern or specific application. The purpose of a SIG is to:

- provide a natural extension of the workshop until the commencement of the next workshop;
- serve as a means for members of several companies to engage in a collaborative pursuit of knowledge and understanding of these topics of interest; and,
- develop solutions or solution methodologies.

Each SIG has a designated chairperson who guides the SIG discussions and meetings during the workshops, and after the workshop adjournments, fosters intra-SIG communications until the commencement of the following workshops.

Minimum requirements of SIG Chairperson:

- Guide the SIG meeting(s) at IRW & at other symposiums when appropriate.
- Maintain an updated charter and publish minutes from meetings.
- Disseminate communications among SIG members using EMAIL.

Each SIG Chairperson needs to put together an EMAIL distribution list for their respective SIG and to initiate and foster the initial and future communications. Any SIG member with either information to share or in need of information is then encouraged to avail themselves to phone and EMAIL communications.

### SURVEY RESULTS

<u>SIG /applicant interest</u>	<u>SIG Chair</u>	<u>Affiliation</u>	<u>Phone</u>
Electromigration* (17)	Marty Johnson	NSC	408-721-3077
WLR Implementation* (16)	Gordon Claudius	Rockwell	714-833-4060
Thin Oxides* (14)	Cleston Messick	NSC	801-562-7546
Hot Carrier (13)	Eric Snyder	Sandia	505-845-8577
ESD (12)	Marty Frary	Storage Tech.	303-673-7537
HAST* (10)	David Wilkie	Microchip	602-786-7415
Thick Ox. Diel. Integrity (7)	David Huang	Cirrus Log	214-995-1011
Mobile Ion (7)	Mark Poulter	NSC	408 -721 -8472
Wafer/Die Level B.I.* (7)	David Kirshner	Sharp	206 -834-8777
Test Chip Design (7)	Harry Schafft	NIST	301-975-2234
Package Rel. Test Chip* (6)	James Sweet	Sandia	505-845-8242
Latch-Up (6)	<b>(volunteer needed)</b>		
Charge Monitor* (5)	Wes Lukaszek	W.C.M.	415-851-9313
Spin-On Glass (5)	<b>(volunteer needed)</b>		
Stress Migration (4)	Jay Shideler	NSC	408-721-7558
Rel. Simulation Tools/Mod. (4)	Ping-Chung Li	AMD	408-749-6549

\* designates an original SIG.

**SIG SURVEY ROSTER****Electromigration (17): Marty Johnson**

David Huang	Mark Poulter	Ko Noguchi
Douglas Brisbin	Samy El-Guebaly	Jeff May
Boris Lisenker	James Molyneaux	Lawrence Clark
Horst Rempp	Ping-Chung Li	Shekhar Khandekar
Jeong Soo Byun	Chiara Zaccherini	Paul Syudergard
Gene Lyons	Don Pierce	

**WLR Implementation (16): Gordon Cladius**

David Huang	James Molyneaux	Mark Hensen
Boris Lisenker	Jenn Luen Yeh	David Wilkie
Tom Kopley	Brad Moore	Shekhar Khandekar
Eric Rabago	Jeff May	Chiara Zuccherini
Gene Lyons	Don Pierce	Sheng-Yang Huang
Martin Duncan		

**Thin Oxide (14): Cleston Messick**

David Huang	Samy El-Guebaly	Vishwas Bhide
Douglas Brisbin	Ping-Chung Li	Mark Hensen
Tom Kopley	Ko Noguchi	John Berk
Mark Poulter	Brad Moore	David Wilkie
Andreas Martin	Martin Duncan	

**Hot Carrier (13): Eric Snyder**

David Huang	Horst Rempp	Brad Moore
Douglas Brisbin	Mark Poulter	Vishwas Bhide
Boris Lisenker	Ping-Chung Li	Jeff May
Tom Kopley	Jenn Luen Yeh	Lawrence Clark
Gene Lyons		

**ESD (12): Martv Fray**

Tin Yau Ying	Mark Hensen	Paul Syudergard
Samy El-Guebaly	John Berk	Gene Lyons
David Kirchner	David Wilkie	Don Pierce
Vishwas Bhide	Shekhar Khandekar	Dennis Eaton

**HAST (10): (Brian Walker)**

Mark Poulter	John Berk	Chiara Zaccherini
David Wilkie	Paul Syudergard	James Molyneaux
Lee Yelshin	Pradip Patel	Shekhar Khandekar
Dennis Eaton		

**Thick Ox. Diel. Integrity (7):(?)**

David Huang	Horst Rempp	Chiara Zaccherini
Douglas Brisbin	Mark Poulter	
Boris Lisenker	Andreas Martin	

**Mobile Ion (7):!D**

David Huang	Mark Poulter	Gene Lyons
Douglas Brisbin	David Kirchner	
Boris Lisenker	George West	

**Wafer/Die Level B.I. (7): David Kirshner**

Lee Yelshin	David Wilkie	Don Pierce
David Kirchner	Dennis Eaton	Shekhar Khandekar
Hirsch Goffman		

**Test Chip Design (7): Harv Schafft (?)**

Mark Poulter	Mark Hensen	Sheng-Yang Huang
Lee Yelshin	Don Pierce	
Vishwas Bhide	Pradip Patel	

**Package Rel. Test Chip (6): James Sweet**

Jenn Luen Yeh	Gene Lyons	James Molyneaux
Lee Yelshin	David Wilkie	Pradip Patel

**Latch-Up(6):(?)**

Mark Hensen	David Wilkie	Samy El-Guebaly
Jenn Luen Yeh	John Berk	Shekhar Khandekar

**Charge Monitor (S): Wes lukaszek**

Ko Noguchi	Mark Hensen	Martin Duncan
Vishwas Bhide	John Berk	

**Spin-On-Glass (5): Mark Poulter (?)**

Mark Poulter	David Wilkie	George West
Mark Hensen	Chiara Zaccherini	

**Stress Migration (4): Jay Shideler**

Douglas Brisbin	Jeff May
Mark Poulter	Paul Syudergard

**Rel. Simulation Tools/Mod. (4):(?)**

Tin Yau Ying	Ping-Chung Li
Lawrence Clark	Lee Yelshin

**Known Good Die (2):2**

Lee Yelshin	David Kirchner
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**Soft Error Rate (1): ..... David Kirchner****Life Time Predictions B ..... Andraes Martin****Statistics (1)- ..... Andraes Martin****EEPROM Endurance (1): ..... David Wilkie**